



FIG. 1A

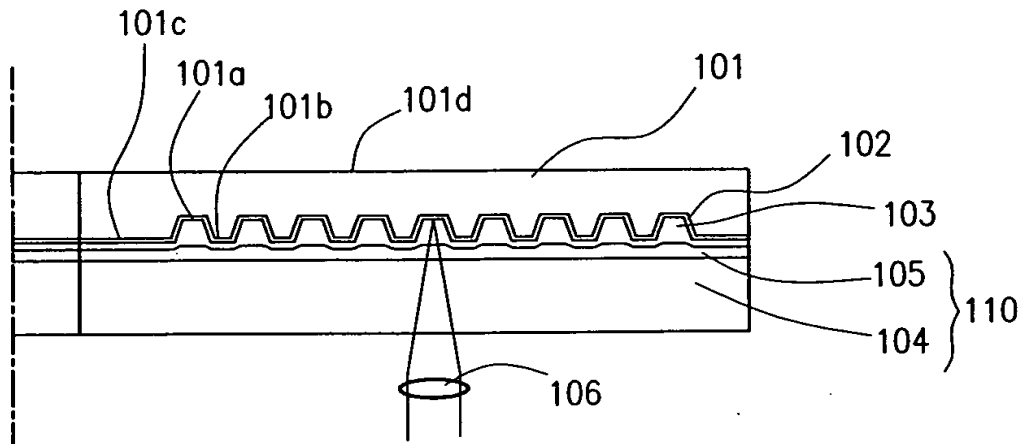
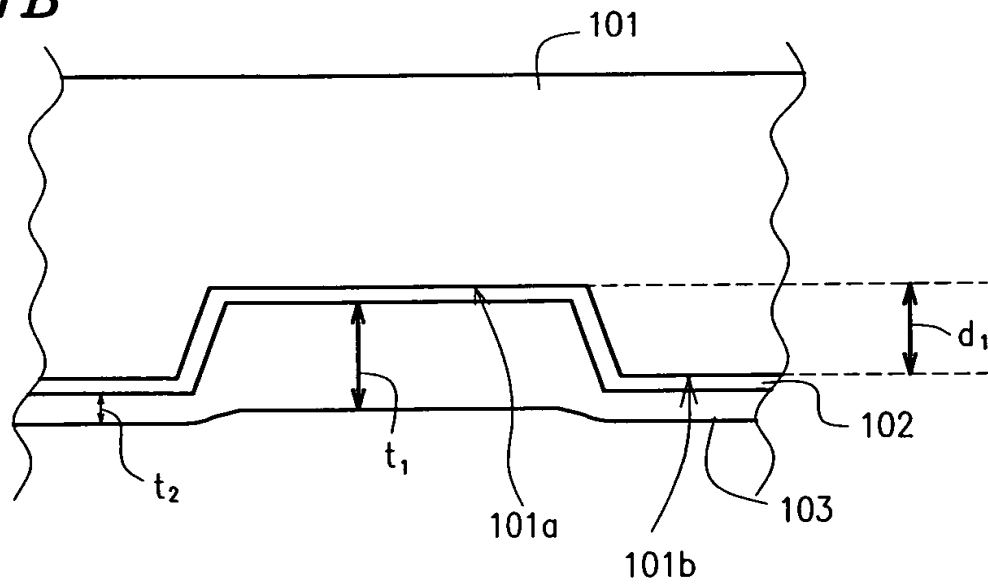


FIG. 1B



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FIG. 2

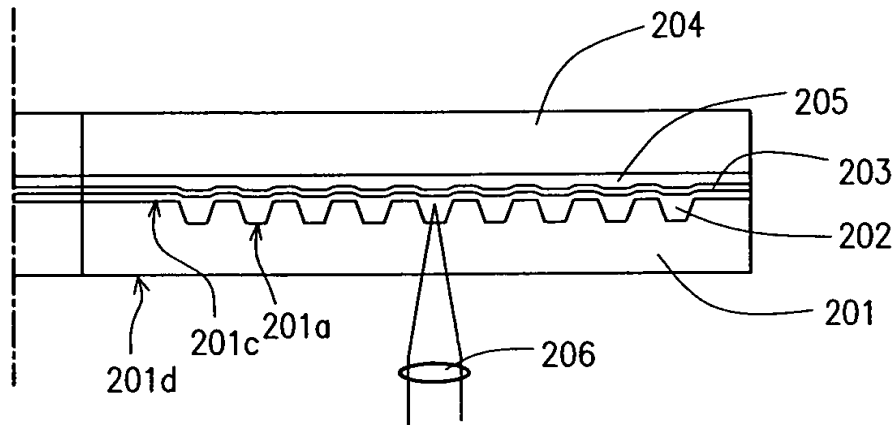
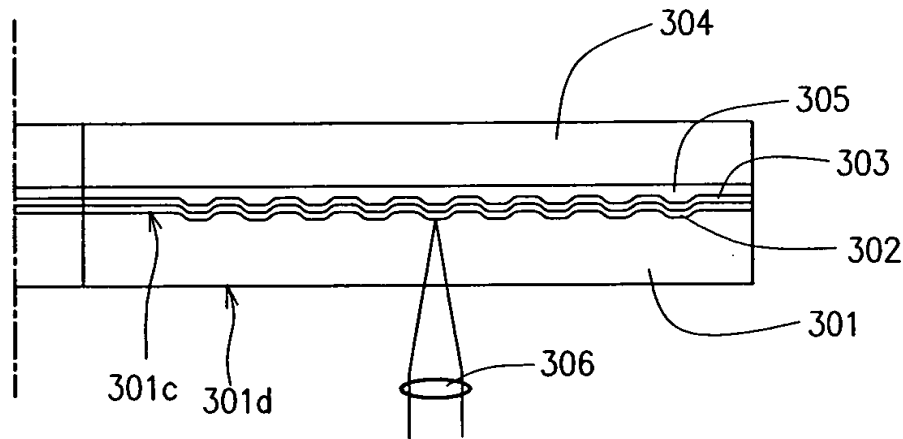
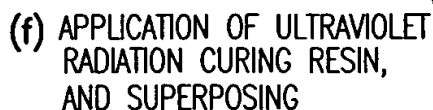
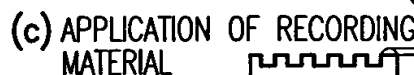


FIG. 3



FABRICATION STEP OF FIRST SUBSTRATE

(a) INJECTION MOLDING

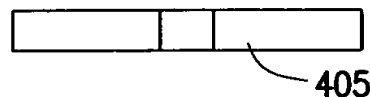


(g) SPIN BONDING

(h) CURING BY APPLICATION OF ULTRAVIOLET RADIATION

(i)

(e) INJECTION MOLDING



BONDING STEP

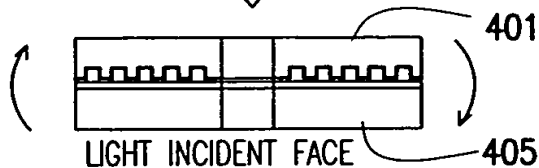
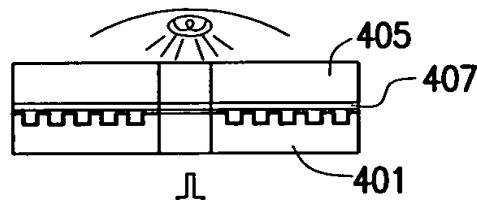
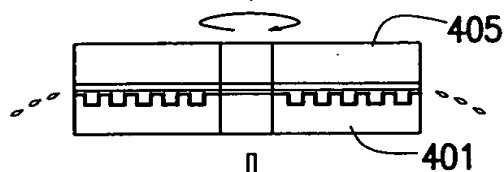
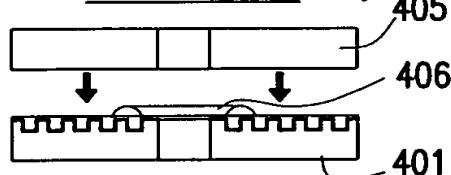


FIG. 5

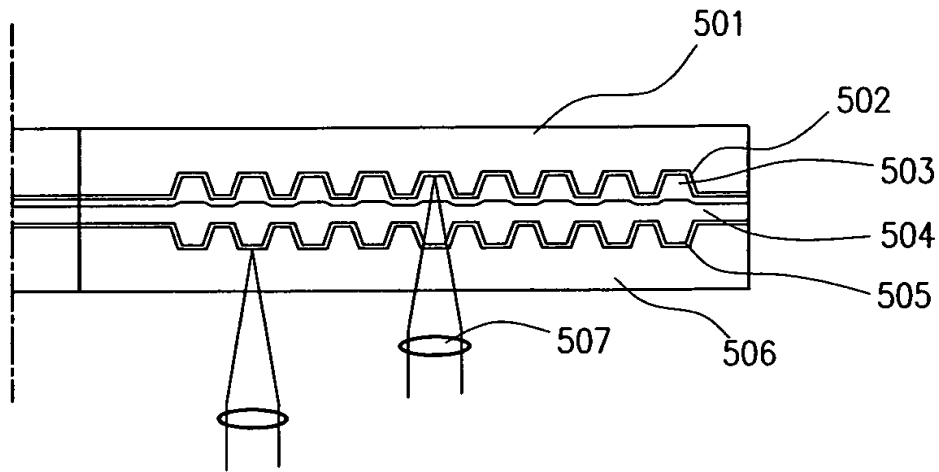
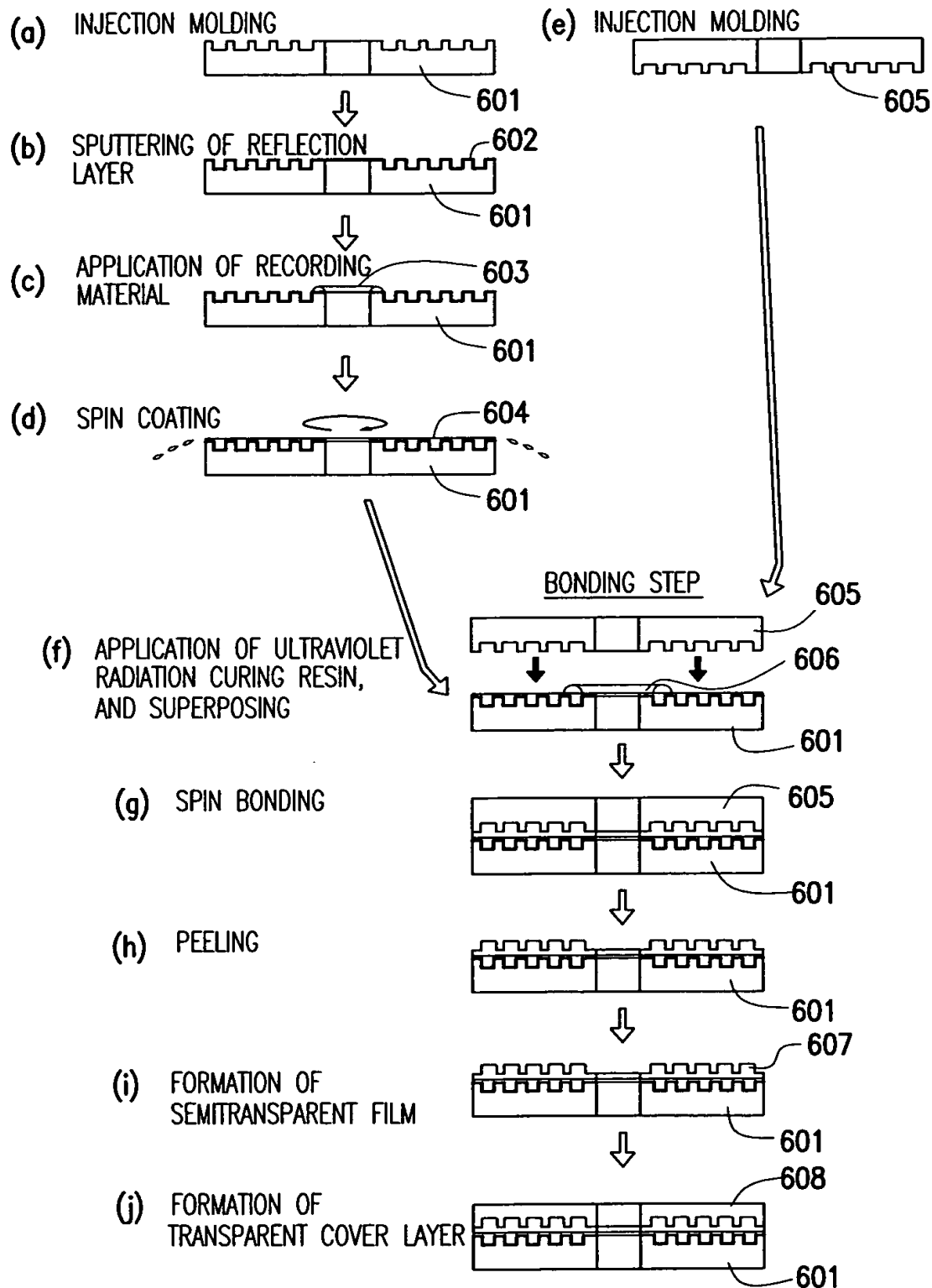


FIG. 5

FIG. 6

FABRICATION STEP OF
FIRST SUBSTRATE

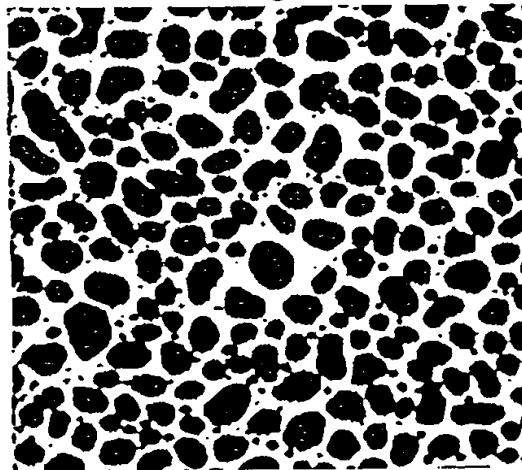
FABRICATION STEP OF
SECOND SUBSTRATE



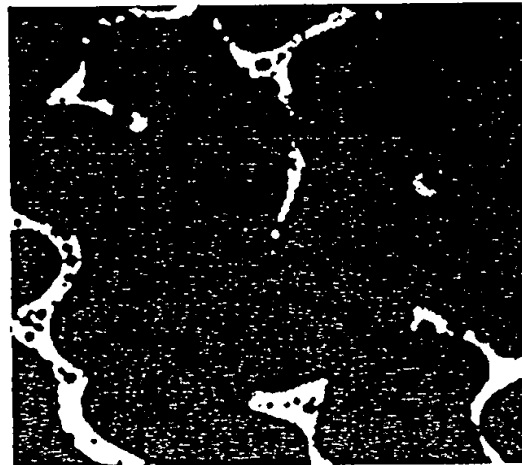
(a)



(b)



(c)



FILM THICKNESS : 55nm